



ASM International N.V.

ASM Receives Order from China's Global Advanced Packaging Technology Ltd. For Eagle Wire Bonders

BILTHOVEN, The Netherlands, February 17, 2004 --- ASM International N.V.

(Nasdaq: ASMI and Euronext Amsterdam: ASM) today announced that its 54%-owned subsidiary, ASM Pacific Technology, Ltd. (Hong Kong Exchanges: 0522) has received an initial order for its Eagle 60 gold wire bonder from Global Advanced Packaging Technology Ltd. (GAPT) in Shanghai, one of China's leading packaging companies. Delivery of the bonders to GAPT's facility will be completed in the current quarter.

C.K. Lin, President of GAPT, said, "We selected ASM's Eagle 60 gold wire bonder because of its high throughput and fine pitch capability that is necessary for our advanced packaging designs, which include chip array and plastic BGAs (Ball Grid Arrays), stack die, and other fine pitch packages. Additionally, we feel very comfortable with the support and service system provided by a local global supplier like ASMPT."

"This order is especially significant to us because GAPT is one of the most important new packaging companies in China," commented Patrick Lam, Managing Director of ASM Pacific Technology. "They are also among the few subcontractors in China making the most advanced chip packages for high-end applications, such as the mobile device and communications market."

Launched in 2002, ASM's award-winning Eagle 60 gold wire bonder is the industry's first production machine capable of 35-micron fine pitch bonding – one generation ahead of its leading competitors. Offering 20 percent higher productivity than its predecessor model, the Eagle 60 received the Advanced Packaging Magazine Award for wire bonders in 2003.

About GAPT

Global Advanced Packaging Technology Limited, located in Zhangjiang Hi-Tech Park in the Pudong District of Shanghai, China. The Company plans to invest hundreds of million US dollars to establish a complete packaging design, assembly testing and bumping enterprise. GAPT will cooperate with IC design and wafer processing companies in the park to deliver "one-stop-shopping" to customers in China and worldwide. The products GAPT tests include consumer, communications and computer semiconductor devices. For more information, please visit: www.GAPTL.com.



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About ASM and ASMPT

ASM International N.V. is headquartered in Bilthoven, the Netherlands. ASM International is a global company, serving one of the most important and demanding industries in the world. The Company possesses a strong technological base, state-of-the-art manufacturing facilities, a competent and qualified workforce and a highly trained, strategically distributed support network. ASM International's subsidiaries design and manufacture equipment and materials used to produce semiconductor devices. ASM International and its subsidiaries provide production solutions for wafer processing, assembly and packaging through their facilities in the United States, Europe, Japan and Asia. ASM International's common stock shares trade on Nasdaq (symbol ASMI) and the Euronext Stock Exchange in Amsterdam (symbol ASM). For more information, visit ASM's web site at <http://www.asm.com>

ASM Pacific Technology, Ltd. with headquarters in Hong Kong, has operations in Shenzhen China, Singapore and Malaysia. It is the world's largest supplier of a full line of assembly and packaging equipment for the semiconductor industry. It also supplies the Photonics and Optoelectronics markets. With its financial strength and R&D resources, ASMPT offers its customers total solutions in process innovations, package development and factory automation. ASMPT is 54%-owned by ASM International N.V. ASM Pacific Technology, Ltd. common shares trade on the Hong Kong Exchanges under the symbol: 0522. For more information, visit ASMPT's web site at www.asmpacific.com

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